

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

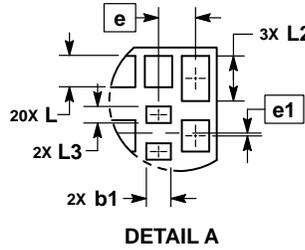
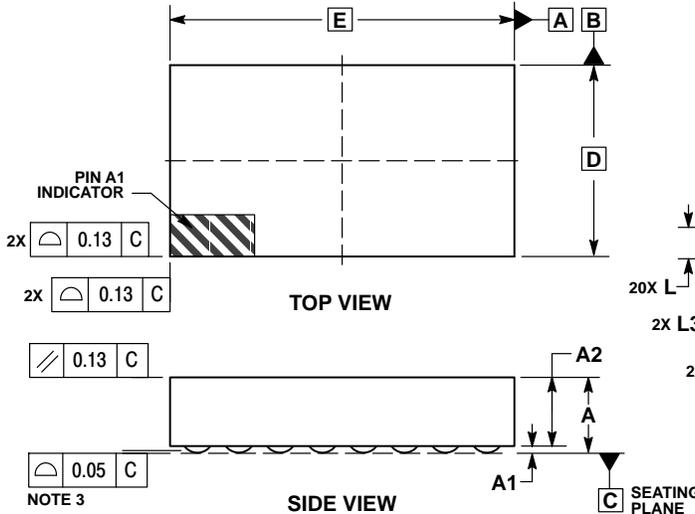
ON Semiconductor®



SCALE 2:1

SIP25, 5.72x3.18
CASE 127DZ
ISSUE O

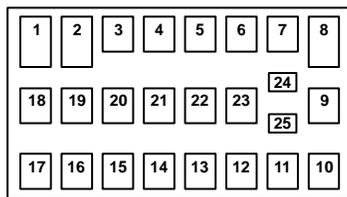
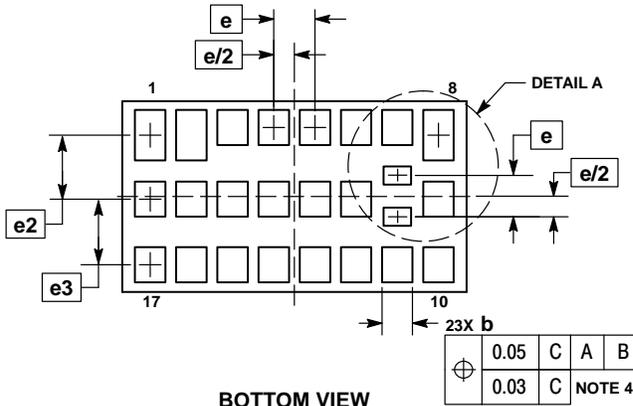
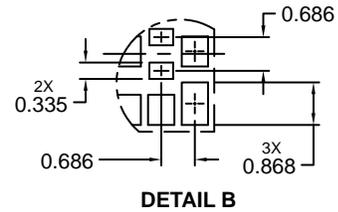
DATE 20 APR 2016



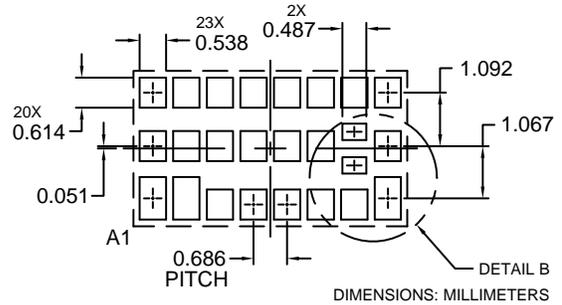
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE PADS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	1.31
A1	0.07	0.17
A2	---	1.14
b	0.478	0.538
b1	0.427	0.487
D	3.18 BSC	
E	5.72 BSC	
e	0.686 BSC	
e1	0.051 BSC	
e2	1.067 BSC	
e3	1.092 BSC	
L	0.554	0.614
L2	0.808	0.868
L3	0.275	0.335



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SIP25, 5.72X3.18	PAGE 1 OF 2

